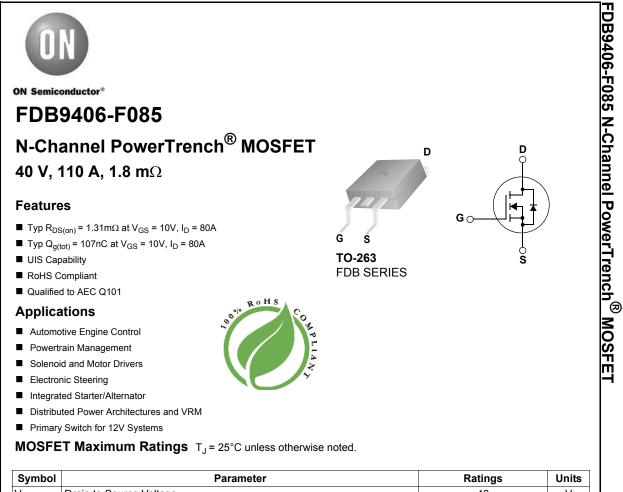
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Symbol	Parameter		Ratings	Units
V _{DSS}	Drain to Source Voltage		40	V
V _{GS}	Gate to Source Voltage		±20	V
	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C = 25°C	110	^
I _D	Pulsed Drain Current	T _C = 25°C	See Figure4	Α
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	174	mJ
-	Power Dissipation		176	W
PD	Derate above 25°C		1.18	W/ºC
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.85	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB9406	FDB9406-F085	D2-PAK(TO-263)	330mm	24mm	800 units

Notes:

1: Current is limited by bondwire configuration. 2: Starting $T_J = 25^{\circ}$ C, L = 0.045mH, I_{AS} = 88A, V_{DD} = 40V during inductor charging and V_{DD} = 0V during time in avalanche. 3: R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder

mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Cha	racteristics					
B _{VDSS}	Drain-to-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	40	-	-	V
	Drain-to-Source Leakage Current	V_{DS} =40V, T_J =25°C	-	-	1	μA
IDSS	Dialit-to-Source Leakage Current	$V_{GS} = 0V$ $T_J = 175^{\circ}C(Note 4)$	-	-	1	mA
I _{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 20V$	-	-	±100	nA
R _{DS(on)}	Drain-to-Source On Resistance	$I_{\rm D} = 80A, \qquad T_{\rm J} = 25^{\circ}C$	-	1.31	1.8	mΩ
		V_{GS} = 10V T_{J} = 175°C(Note 4)	-	2.2	2.8	mΩ
Jynami	c Characteristics					
C _{iss}	Input Capacitance		-	7710	-	pF
C _{oss}	Output Capacitance	─V _{DS} = 25V, V _{GS} = 0V, f = 1MHz	-	2015	-	pF
C _{rss}	Reverse Transfer Capacitance	1 - 110112	-	140	-	pF
R _g	Gate Resistance	f = 1MHz	-	2.7	-	Ω
Q _{g(ToT)}	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V $V_{DD} = 32V$	-	107	138	nC
	Thursday of the Orly and		-	14	19	nC
Q _{g(th)}	Threshold Gate Charge	$V_{GS} = 0$ to 2V $I_D = 80A$	_	14	10	
Q _{g(th)} Q _{gs}	Gate-to-Source Gate Charge	$V_{GS} = 0.02V$ $I_D = 80A$	-	33	-	nC

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Switching Characteristics

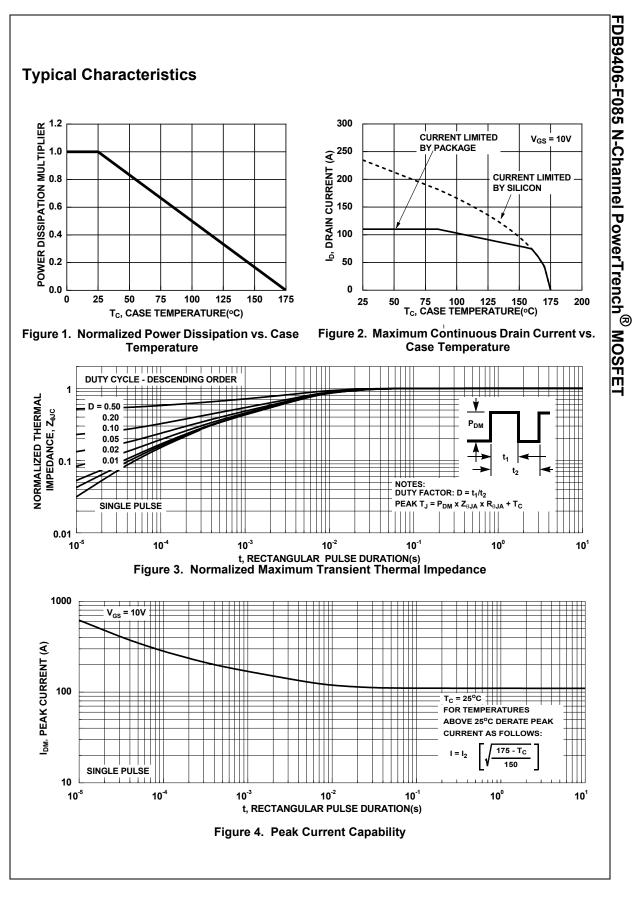
t _{on}	Turn-On Time		-	-	160	ns
t _{d(on)}	Turn-On Delay		-	32	-	ns
t _r	Rise Time	V _{DD} = 20V, I _D = 80A,	-	81	-	ns
t _{d(off)}	Turn-Off Delay	V_{DD} = 20V, I _D = 80A, V _{GS} = 10V, R _{GEN} = 6Ω	-	50	-	ns
t _f	Fall Time		-	23	-	ns
t _{off}	Turn-Off Time		-	-	93	ns

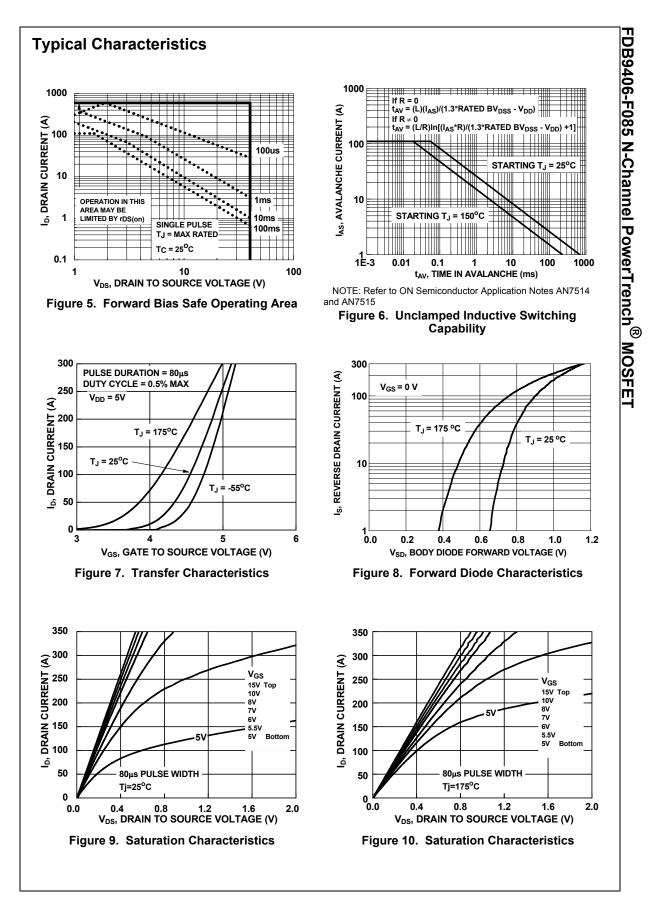
Drain-Source Diode Characteristics

V_{SD}	Source-to-Drain Diode Voltage	I _{SD} = 80A, V _{GS} = 0V	-	-	1.25	V
t _{rr}	Reverse-Recovery Time	I _F = 80A, dI _{SD} /dt = 100A/μs,	-	85	110	ns
Q _{rr}	Reverse-Recovery Charge	V _{DD} =32V	-	122	160	nC

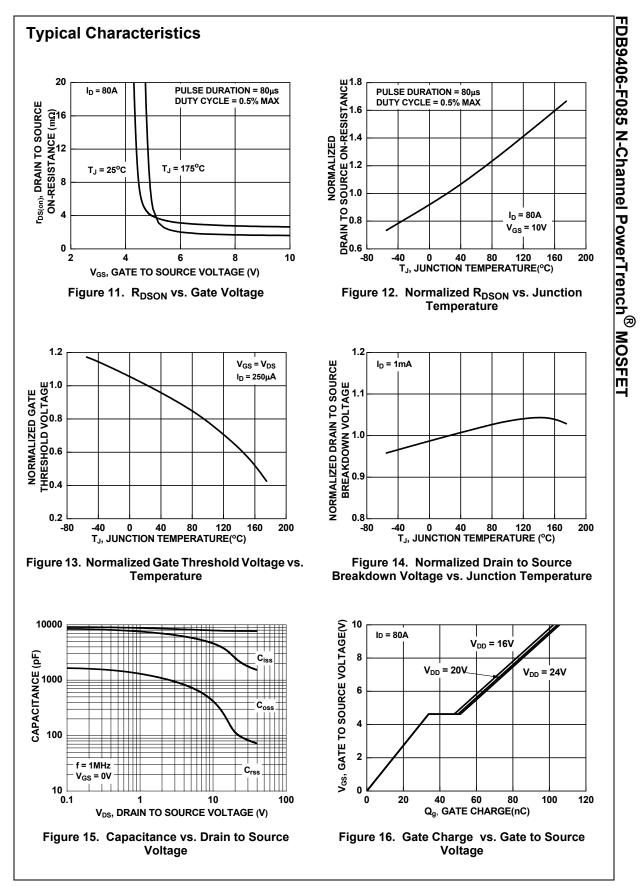
Note:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.





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